Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	I²C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	91
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	14K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	112-LQFP
Supplier Device Package	112-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12a512cpve

Version Number	Revision Date	Effective Date	Author	Description of Changes
V01.16	31 Mar 2003	31 Mar 2003		- Corrections in App. A 'NVM, Flash and EEPROM': - Number of words per flash row = 64 - Replaced 'burst programming' with 'row programming' - Sector erase size = 1024 bytes - Corrected feature description ECT - Corrected min. bus freq. in table 'Operating Conditions'
V01.17	30 May 2003	30 May 2003		- Replaced references to HCS12 Core Guide with the individual HCS12 Block guides throughout document - Table 'Absolute Maximum Ratings' corrected footnote on clamp of TEST pin
V01.18	23 Jul 2003	23 Jul 2003		- Mentioned 'S12 LRAE' bootloader in Flash section - Document References: corrected S12 CPU document reference
V01.19	24 Jul 2003	24 Jul 2003		- Added part ID for 2L00M maskset.
V01.20	01 Sep 2003	01 Sep 2003		- Added part ID for 3L00M maskset. - Added cycle definition to 'CPU 12 Block Description'. - Diagram 'Clock Connections': Connected Bus Clock to HCS12 Core. - Corrected 'Background Debug Module' to 'HCS12 Breakpoint' at address $0028 - $002F in table 1-1. - Corrected 'Blank Check Time Flash' value in table 'NVM Timing Characteristics' - Added EXTAL pin VIH, VIL and EXTAL pin hysteresis value to 'Oscillator Characteristics'. Updated oscillator description and table note.
V01.21	08 Mar 2004	08 Mar 2004		- Added part ID for 4L00M maskset. - Corrected pin name KWP5 in device pinout.
V01.22	23 Aug 2004	23 Aug 2004		- Updated $V_{IH,EXTAL}$ and $V_{IL,EXTAL}$ in table 'Oscillator Characteristics' - Removed item 'Oscillator' from table 'Operating Conditions' as already covered in table 'Oscillator Characteristics'
V01.23	09 Feb 2005	09 Feb 2005		- Corrected Flash Row Programming Time in NVM Timing Characteristics
V01.24	01 Apr 2005	01 Apr 2005		- Changed T_{Javg} and added footnote to data retention time in NVM Reliability Characteristics
V01.25	05 Jul 2005	05 Jul 2005		- Updated NVM Reliability Characteristics

List of Figures

NOTES:
1. Reused due to functional equivalence.

$0034 - $003F CRG (Clock and Reset Generator)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0039	CLKSEL	Read:	PLLSEL	PSTP	SYSWAI	ROAWAI	PLLWAI	CWAI	RTIWAI	COPWAI
		Write:								
$003A	PLLCTL	Read:	CME	PLLON	AUTO	ACQ	0	PRE	PCE	SCME
		Write:								
$003B	RTICTL	Read:	0	RTR6	RTR5	RTR4	RTR3	RTR2	RTR1	RTR0
		Write:								
$003C	COPCTL	Read:	WCOP	RSBCK	0	0	0	CR2	CR1	CR0
		Write:								
$003D	FORBYP Test Only	Read:	RTIBYP	COPBYP	0	PLLBYP	0	0	FCM	0
		Write:								
$003E	CTCTL Test Only	Read:	TCTL7	TCTL6	TCTL5	TCTL4	TCLT3	TCTL2	TCTL1	TCTL0
		Write:								
$003F	ARMCOP	Read:	0	0	0	0	0	0	0	0
		Write:	Bit 7	6	5	4	3	2	1	Bit 0

$0040 - $007F ECT (Enhanced Capture Timer 16 Bit 8 Channels)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0040	TIOS	Read:	IOS7	IOS6	IOS5	IOS4	IOS3	IOS2	IOS1	IOS0
		Write:								
$0041	CFORC	Read:	0	0	0	0	0	0	0	0
		Write:	FOC7	FOC6	FOC5	FOC4	FOC3	FOC2	FOC1	FOC0
$0042	OC7M	Read:	OC7M7	OC7M6	OC7M5	OC7M4	OC7M3	OC7M2	OC7M1	OC7M0
		Write:								
$0043	OC7D	Read:	OC7D7	OC7D6	OC7D5	OC7D4	OC7D3	OC7D2	OC7D1	OC7D0
		Write:								
$0044	TCNT (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$0045	TCNT (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$0046	TSCR1	Read:	TEN	TSWAI	TSFRZ	TFFCA	0	0	0	0
		Write:								
$0047	TTOV	Read:	TOV7	TOV6	TOV5	TOV4	TOV3	TOV2	TOV1	TOV0
		Write:								
$0048	TCTL1	Read:	OM7	OL7	OM6	OL6	OM5	OL5	OM4	OL4
		Write:								
$0049	TCTL2	Read:	OM3	OL3	OM2	OL2	OM1	OL1	OM0	OL0
		Write:								
$004A	TCTL3	Read:	EDG7B	EDG7A	EDG6B	EDG6A	EDG5B	EDG5A	EDG4B	EDG4A
		Write:								
$004B	TCTL4	Read:	EDG3B	EDG3A	EDG2B	EDG2A	EDG1B	EDG1A	EDG0B	EDG0A
		Write:								
$004C	TIE	Read:	C7I	C6I	C5I	C4I	C3I	C2I	C1I	C0I
		Write:								
$004D	TSCR2	Read:	TOI	0	0	0	TCRE	PR2	PR1	PR0
		Write:								
$004E	TFLG1	Read:	C7F	C6F	C5F	C4F	C3F	C2F	C1F	C0F
		Write:								

$00C8 - $00CF SCI0 (Asynchronous Serial Interface)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00C8	SCI0BDH	Read:	0	0	0	SBR12	SBR11	SBR10	SBR9	SBR8
		Write:								
$00C9	SCI0BDL	Read:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
		Write:								
$00CA	SC0CR1	Read:	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
		Write:								
$00CB	SCI0CR2	Read:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
		Write:								
$00CC	SCI0SR1	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
		Write:								
$00CD	SC0SR2	Read:	0	0	0	0	0	BRK13	TXDIR	RAF
		Write:								
$00CE	SCI0DRH	Read:	R8	T8	0	0	0	0	0	0
		Write:								
$00CF	SCI0DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0

$00D0 - $00D7 SCI1 (Asynchronous Serial Interface)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00D0	SCI1BDH	Read:	0	0	0	SBR12	SBR11	SBR10	SBR9	SBR8
		Write:								
$00D1	SCI1BDL	Read:	SBR7	SBR6	SBR5	SBR4	SBR3	SBR2	SBR1	SBR0
		Write:								
$00D2	SC1CR1	Read:	LOOPS	SCISWAI	RSRC	M	WAKE	ILT	PE	PT
		Write:								
$00D3	SCI1CR2	Read:	TIE	TCIE	RIE	ILIE	TE	RE	RWU	SBK
		Write:								
$00D4	SCI1SR1	Read:	TDRE	TC	RDRF	IDLE	OR	NF	FE	PF
		Write:								
$00D5	SC1SR2	Read:	0	0	0	0	0	BRK13	TXDIR	RAF
		Write:								
$00D6	SCI1DRH	Read:	R8	T8	0	0	0	0	0	0
		Write:								
$00D7	SCI1DRL	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0

$00D8 - $00DF SPI0 (Serial Peripheral Interface)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00D8	SPI0CR1	Read:	SPIE	SPE	SPTIE	MSTR	CPOL	CPHA	SSOE	LSBFE
		Write:								
$00D9	SPI0CR2	Read:	0	0	0	MODFEN	BIDIROE	0	SPISWAI	SPC0
		Write:								
$00DA	SPI0BR	Read:	0	SPPR2	SPPR1	SPPR0	0	SPR2	SPR1	SPR0
		Write:								
$00DB	SPI0SR	Read:	SPIF	0	SPTEF	MODF	0	0	0	0
		Write:								

Pin Name Funct. 1	Pin Name Funct. 2	Pin Name Funct. 3	Pin Name Funct. 4	Pin Name Funct. 5	Power Supply	Internal Pull Resistor		Description
						CTRL	Reset State	
PH7	KWH7	$\overline{SS2}$	—	—	VDDR	PERH/ PPSH	Disabled	Port H I/O, Interrupt, $\overline{SS}$ of SPI2
PH6	KWH6	SCK2	—	—				Port H I/O, Interrupt, SCK of SPI2
PH5	KWH5	MOSI2	—	—				Port H I/O, Interrupt, MOSI of SPI2
PH4	KWH4	MISO2	—	—				Port H I/O, Interrupt, MISO of SPI2
PH3	KWH3	$\overline{SS1}$	—	—				Port H I/O, Interrupt, $\overline{SS}$ of SPI1
PH2	KWH2	SCK1	—	—				Port H I/O, Interrupt, SCK of SPI1
PH1	KWH1	MOSI1	—	—				Port H I/O, Interrupt, MOSI of SPI1
PH0	KWH0	MISO1	—	—				Port H I/O, Interrupt, MISO of SPI1
PJ7	KWJ7	TXCAN4	SCL	TXCAN0	VDDX	PERJ/ PPSJ	Up	Port J I/O, Interrupt, TX of CAN4, SCL of IIC, TX of CAN0
PJ6	KWJ6	RXCAN4	SDA	RXCAN0				Port J I/O, Interrupt, RX of CAN4, SDA of IIC, RX of CAN0
PJ[1:0]	KWJ[1:0]	—	—	—				Port J I/O, Interrupts
PK7	$\overline{ECS}$	ROMCTL	—	—	VDDX	PUCR/ PUPKE	Up	Port K I/O, Emulation Chip Select, ROM Control
PK[5:0]	XADDR [19:14]	—	—	—				Port K I/O, Extended Addresses
PM7	TXCAN3	TXCAN4	—	—	VDDX	PERM/ PPSM	Disabled	Port M I/O, TX of CAN3, TX of CAN4
PM6	RXCAN3	RXCAN4	—	—				Port M I/O, RX of CAN3, RX of CAN4
PM5	TXCAN2	TXCAN0	TXCAN4	SCK0				Port M I/O, TX of CAN2, CAN0, CAN4, SCK of SPI0
PM4	RXCAN2	RXCAN0	RXCAN4	MOSI0				Port M I/O, RX of CAN2, CAN0, CAN4, MOSI of SPI0
PM3	TXCAN1	TXCAN0	—	$\overline{SS0}$				Port M I/O, TX of CAN1, CAN0, $\overline{SS}$ of SPI0
PM2	RXCAN1	RXCAN0	—	MISO0				Port M I/O, RX of CAN1, CAN0, MISO of SPI0
PM1	TXCAN0	TXB	—	—				Port M I/O, TX of CAN0, RX of BDLC
PM0	RXCAN0	RXB	—	—				Port M I/O, RX of CAN0, RX of BDLC
PP7	KWP7	PWM7	SCK2	—	VDDX	PERP/ PPSP	Disabled	Port P I/O, Interrupt, Channel 7 of PWM, SCK of SPI2
PP6	KWP6	PWM6	$\overline{SS2}$	—				Port P I/O, Interrupt, Channel 6 of PWM, $\overline{SS}$ of SPI2
PP5	KWP5	PWM5	MOSI2	—				Port P I/O, Interrupt, Channel 5 of PWM, MOSI of SPI2
PP4	KWP4	PWM4	MISO2	—				Port P I/O, Interrupt, Channel 4 of PWM, MISO2 of SPI2
PP3	KWP3	PWM3	$\overline{SS1}$	—				Port P I/O, Interrupt, Channel 3 of PWM, $\overline{SS}$ of SPI1
PP2	KWP2	PWM2	SCK1	—				Port P I/O, Interrupt, Channel 2 of PWM, SCK of SPI1
PP1	KWP1	PWM1	MOSI1	—				Port P I/O, Interrupt, Channel 1 of PWM, MOSI of SPI1
PP0	KWP0	PWM0	MISO1	—				Port P I/O, Interrupt, Channel 0 of PWM, MISO2 of SPI1

2.3.5 XFC — PLL Loop Filter Pin

PLL loop filter. Please ask your Freescale representative for the interactive application note to compute PLL loop filter elements. Any current leakage on this pin must be avoided.

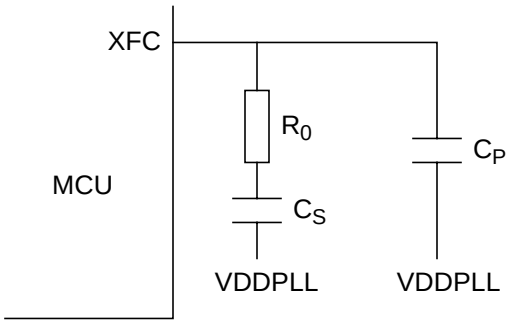


Figure 2-2 PLL Loop Filter Connections

2.3.6 BKGD / $\overline{\text{TAGHI}}$ / MODC — Background Debug, Tag High, and Mode Pin

The BKGD/$\overline{\text{TAGHI}}$/MODC pin is used as a pseudo-open-drain pin for the background debug communication. In MCU expanded modes of operation when instruction tagging is on, an input low on this pin during the falling edge of E-clock tags the high half of the instruction word being read into the instruction queue. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODC bit at the rising edge of $\overline{\text{RESET}}$. This pin has a permanently enabled pull-up device.

2.3.7 PAD15 / AN15 / ETRIG1 — Port AD Input Pin of ATD1

PAD15 is a general purpose input pin and analog input AN7 of the analog to digital converter ATD1. It can act as an external trigger input for the ATD1.

2.3.8 PAD[14:08] / AN[14:08] — Port AD Input Pins of ATD1

PAD14 - PAD08 are general purpose input pins and analog inputs AN[6:0] of the analog to digital converter ATD1.

2.3.9 PAD7 / AN07 / ETRIG0 — Port AD Input Pin of ATD0

PAD7 is a general purpose input pin and analog input AN7 of the analog to digital converter ATD0. It can act as an external trigger input for the ATD0.

2.3.10 PAD[06:00] / AN[06:00] — Port AD Input Pins of ATD0

PAD06 - PAD00 are general purpose input pins and analog inputs AN[6:0] of the analog to digital converter ATD0.

$FFCA, $FFCB	Modulus Down Counter underflow	I-Bit	MCCTL (MCZI)	$CA
$FFC8, $FFC9	Pulse Accumulator B Overflow	I-Bit	PBCTL (PBOVI)	$C8
$FFC6, $FFC7	CRG PLL lock	I-Bit	CRGINT (LOCKIE)	$C6
$FFC4, $FFC5	CRG Self Clock Mode	I-Bit	CRGINT (SCMIE)	$C4
$FFC2, $FFC3	BDLC	I-Bit	DLCBCR1 (IE)	$C2
$FFC0, $FFC1	IIC Bus	I-Bit	IBCR (IBIE)	$C0
$FFBE, $FFBF	SPI1	I-Bit	SPICR1 (SPIE, SPTIE)	$BE
$FFBC, $FFBD	SPI2	I-Bit	SPICR1 (SPIE, SPTIE)	$BC
$FFBA, $FFBB	EEPROM	I-Bit	ECNFG (CCIE, CBEIE)	$BA
$FFB8, $FFB9	FLASH	I-Bit	FCNFG (CCIE, CBEIE)	$B8
$FFB6, $FFB7	CAN0 wake-up	I-Bit	CANRIER (WUPIE)	$B6
$FFB4, $FFB5	CAN0 errors	I-Bit	CANRIER (CSCIE, OVRIE)	$B4
$FFB2, $FFB3	CAN0 receive	I-Bit	CANRIER (RXFIE)	$B2
$FFB0, $FFB1	CAN0 transmit	I-Bit	CANTIER (TXEIE2-TXEIE0)	$B0
$FFAE, $FFAF	CAN1 wake-up	I-Bit	CANRIER (WUPIE)	$AE
$FFAC, $FFAD	CAN1 errors	I-Bit	CANRIER (CSCIE, OVRIE)	$AC
$FFAA, $FFAB	CAN1 receive	I-Bit	CANRIER (RXFIE)	$AA
$FFA8, $FFA9	CAN1 transmit	I-Bit	CANTIER (TXEIE2-TXEIE0)	$A8
$FFA6, $FFA7	CAN2 wake-up	I-Bit	CANRIER (WUPIE)	$A6
$FFA4, $FFA5	CAN2 errors	I-Bit	CANRIER (CSCIE, OVRIE)	$A4
$FFA2, $FFA3	CAN2 receive	I-Bit	CANRIER (RXFIE)	$A2
$FFA0, $FFA1	CAN2 transmit	I-Bit	CANTIER (TXEIE2-TXEIE0)	$A0
$FF9E, $FF9F	CAN3 wake-up	I-Bit	CANRIER (WUPIE)	$9E
$FF9C, $FF9D	CAN3 errors	I-Bit	CANRIER (CSCIE, OVRIE)	$9C
$FF9A, $FF9B	CAN3 receive	I-Bit	CANRIER (RXFIE)	$9A
$FF98, $FF99	CAN3 transmit	I-Bit	CANTIER (TXEIE2-TXEIE0)	$98
$FF96, $FF97	CAN4 wake-up	I-Bit	CANRIER (WUPIE)	$96
$FF94, $FF95	CAN4 errors	I-Bit	CANRIER (CSCIE, OVRIE)	$94
$FF92, $FF93	CAN4 receive	I-Bit	CANRIER (RXFIE)	$92
$FF90, $FF91	CAN4 transmit	I-Bit	CANTIER (TXEIE2-TXEIE0)	$90
$FF8E, $FF8F	Port P Interrupt	I-Bit	PIEP (PIEP7-0)	$8E
$FF8C, $FF8D	PWM Emergency Shutdown	I-Bit	PWMSDN (PWMIE)	$8C
$FF80 to $FF8B	Reserved			

5.3 Effects of Reset

When a reset occurs, MCU registers and control bits are changed to known start-up states. Refer to the respective module Block Guides for register reset states.

5.3.1 I/O pins

Refer to the HCS12 Multiplexed External Bus Interface (MEBI) Block Guide for mode dependent pin configuration of port A, B, E and K out of reset.

Refer to the PIM Block Guide for reset configurations of all peripheral module ports.

The "S12 LRAE" is a generic Load RAM and Execute (LRAE) program which will be programmed into the flash memory of this device during manufacture. This LRAE program will provide greater programming flexibility to the end users by allowing the device to be programmed directly using CAN or SCI after it is assembled on the PCB. Use of the LRAE program is at the discretion of the end user and, if not required, it must simply be erased prior to flash programming. For more details of the S12 LRAE and its implementation, please see the S12 LREA Application Note (AN2546/D).

It is planned that most HC9S12 devices manufactured after Q1 of 2004 will be shipped with the S12 LRAE programmed in the Flash. Exact details of the changeover (i.e. blank to programmed) for each product will be communicated in advance via GPCN and will be traceable by the customer via datecode marking on the device.

Please contact Freescale Sales if you have any additional questions.

Section 17 EEPROM 4K Block Description

Consult the EETS4K Block Guide for information about the EEPROM module.

Section 18 RAM Block Description

This module supports single-cycle misaligned word accesses.

Section 19 MSCAN Block Description

There are five MSCAN modules (CAN4, CAN3, CAN2, CAN1 and CAN0) implemented on the MC9S12DP512.

Consult the MSCAN Block Guide for information about the Freescale Scalable CAN Module.

Section 20 Port Integration Module (PIM) Block Description

Consult the functionally equivalent PIM_9DP256 Block Guide for information about the Port Integration Module.

Section 21 Voltage Regulator (VREG) Block Description

Consult the VREG Block Guide for information about the dual output linear voltage regulator.

$$T_J = T_A + (P_D \bullet \Theta_{JA})$$

T_J = Junction Temperature, [°C]

T_A = Ambient Temperature, [°C]

P_D = Total Chip Power Dissipation, [W]

Θ_{JA} = Package Thermal Resistance, [°C/W]

The total power dissipation can be calculated from:

$$P_D = P_{INT} + P_{IO}$$

P_{INT} = Chip Internal Power Dissipation, [W]

Two cases with internal voltage regulator enabled and disabled must be considered:

1. Internal Voltage Regulator disabled

$$P_{INT} = I_{DD} \cdot V_{DD} + I_{DDPLL} \cdot V_{DDPLL} + I_{DDA} \cdot V_{DDA}$$

$$P_{IO} = \sum_i R_{DSON} \cdot I_{IO_i}^2$$

P_{IO} is the sum of all output currents on I/O ports associated with VDDX and VDDR.

For R_{DSON} is valid:

$$R_{DSON} = \frac{V_{OL}}{I_{OL}}; \text{for outputs driven low}$$

respectively

$$R_{DSON} = \frac{V_{DD5} - V_{OH}}{I_{OH}}; \text{for outputs driven high}$$

2. Internal voltage regulator enabled

$$P_{INT} = I_{DDR} \cdot V_{DDR} + I_{DDA} \cdot V_{DDA}$$

I_{DDR} is the current shown in **Table A-7** and not the overall current flowing into VDDR, which additionally contains the current flowing into the external loads with output high.

$$P_{IO} = \sum_i R_{DSON} \cdot I_{IO_i}^2$$

P_{IO} is the sum of all output currents on I/O ports associated with VDDX and VDDR.

Table A-6 5V I/O Characteristics

Conditions are shown in **Table A-4** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	P	Input High Voltage	V_{IH}	$0.65*V_{DD5}$	-	-	V
	T	Input High Voltage	V_{IH}	-	-	VDD5 + 0.3	V
2	P	Input Low Voltage	V_{IL}	-	-	$0.35*V_{DD5}$	V
	T	Input Low Voltage	V_{IL}	VSS5 - 0.3	-	-	V
3	C	Input Hysteresis	V_{HYS}	-	250	-	mV
4	P	Input Leakage Current (pins in high impedance input mode) $V_{in} = V_{DD5}$ or V_{SS5}	I_{in}	–1	-	1	µA
5	P	Output High Voltage (pins in output mode) Partial Drive I_{OH} = –2mA Full Drive I_{OH} = –10mA	V_{OH}	V_{DD5} – 0.8	-	-	V
6	P	Output Low Voltage (pins in output mode) Partial Drive I_{OL} = +2mA Full Drive I_{OL} = +10mA	V_{OL}	-	-	0.8	V
7	P	Internal Pull Up Device Current, tested at V_{IL} Max.	I_{PUL}	-	-	-130	µA
8	C	Internal Pull Up Device Current, tested at V_{IH} Min.	I_{PUH}	-10	-	-	µA
9	P	Internal Pull Down Device Current, tested at V_{IH} Min.	I_{PDH}	-	-	130	µA
10	C	Internal Pull Down Device Current, tested at V_{IL} Max.	I_{PDL}	10	-	-	µA
11	D	Input Capacitance	C_{in}	-	6	-	pF
12	T	Injection current[1] Single Pin limit Total Device Limit. Sum of all injected currents	 I_{ICS} I_{ICP}	 -2.5 -25	-	 2.5 25	mA
13	P	Port H, J, P Interrupt Input Pulse filtered[2]	t_{PIGN}	-	-	3	µs
14	P	Port H, J, P Interrupt Input Pulse passed(2)	t_{PVAL}	10	-	-	µs

NOTES:
1. Refer to **Section A.1.4 Current Injection**, for more details
2. Parameter only applies in STOP or Pseudo STOP mode.

A.1.10 Supply Currents

This section describes the current consumption characteristics of the device as well as the conditions for the measurements.

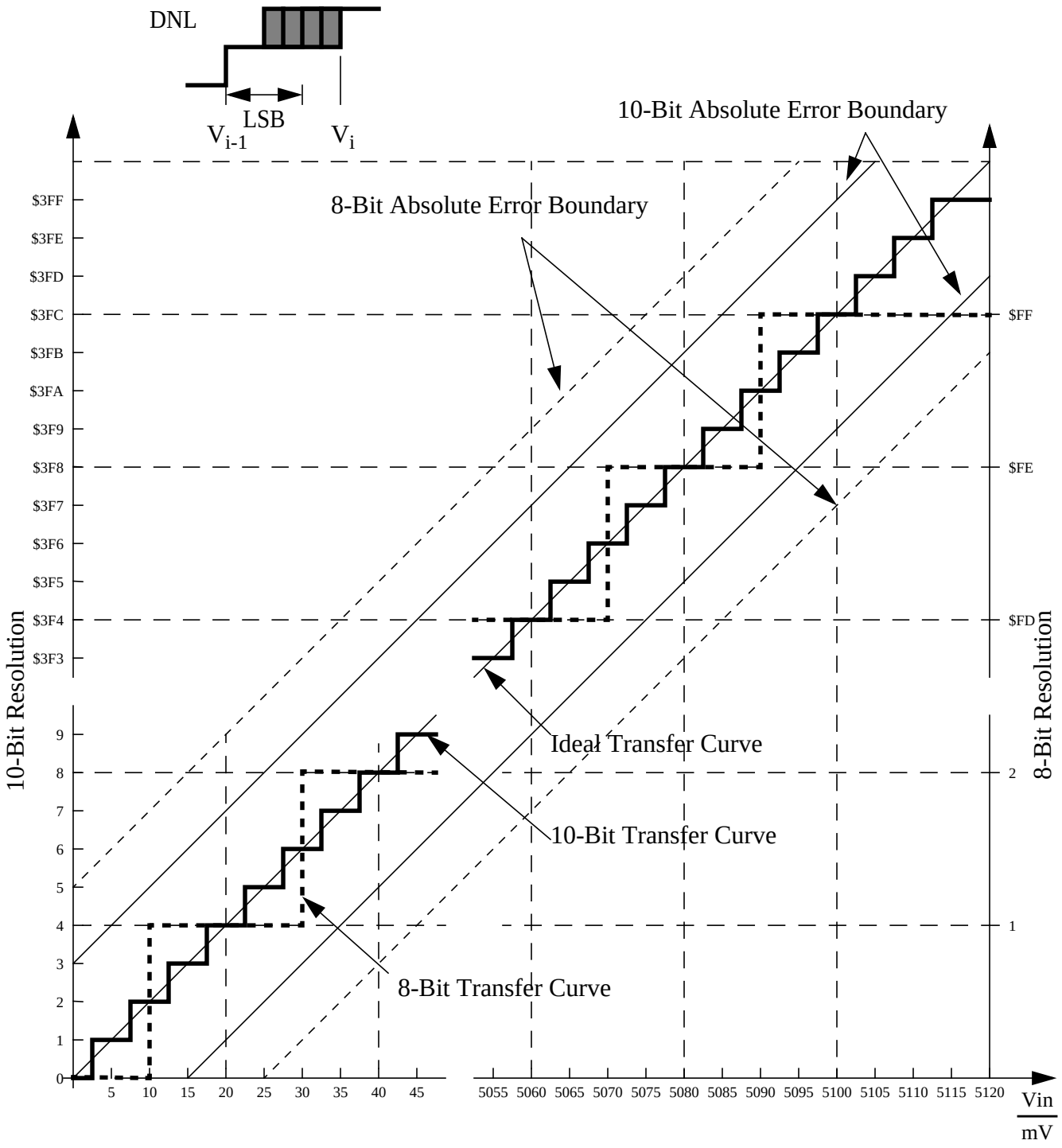


Figure A-1 ATD Accuracy Definitions

NOTE: ***Figure A-1*** *shows only definitions, for specification values refer to* ***Table A-10****.*

A.3.2 NVM Reliability

The reliability of the NVM blocks is guaranteed by stress test during qualification, constant process monitors and burn-in to screen early life failures.

The program/erase cycle count on the sector is incremented every time a sector or mass erase event is executed

Table A-12 NVM Reliability Characteristics[1]

Conditions are shown in **Table A-4** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
Flash Reliability Characteristics							
1	C	Data retention after 10,000 program/erase cycles at an average junction temperature of $T_{Javg} \leq 85°C$	t_{FLRET}	15	100[2]	—	Years
2	C	Data retention with <100 program/erase cycles at an average junction temperature $T_{Javg} \leq 85°C$		20	100[2]	—	
3	C	Number of program/erase cycles ($-40°C \leq T_J \leq 0°C$)	n_{FL}	10,000	—	—	Cycles
4	C	Number of program/erase cycles ($0°C \leq T_J \leq 140°C$)		10,000	100,000[3]	—	
EEPROM Reliability Characteristics							
5	C	Data retention after up to 100,000 program/erase cycles at an average junction temperature of $T_{Javg} \leq 85°C$	t_{EEPRET}	15	100[2]	—	Years
6	C	Data retention with <100 program/erase cycles at an average junction temperature $T_{Javg} \leq 85°C$		20	100[2]	—	
7	C	Number of program/erase cycles ($-40°C \leq T_J \leq 0°C$)	n_{EEP}	10,000	—	—	Cycles
8	C	Number of program/erase cycles ($0°C < T_J \leq 140°C$)		100,000	300,000[3]	—	

NOTES:

1. T_{Javg} will not exeed 85°C considering a typical temperature profile over the lifetime of a consumer, industrial or automotive application.
2. Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25°C using the Arrhenius equation. For additional information on how Freescale defines Typical Data Retention, please refer to Engineering Bulletin EB618.
3. Spec table quotes typical endurance evaluated at 25°C for this product family, typical endurance at various temperature can be estimated using the graph below. For additional information on how Freescale defines Typical Endurance, please refer to Engineering Bulletin EB619.

A.5.1.5 Pseudo Stop and Wait Recovery

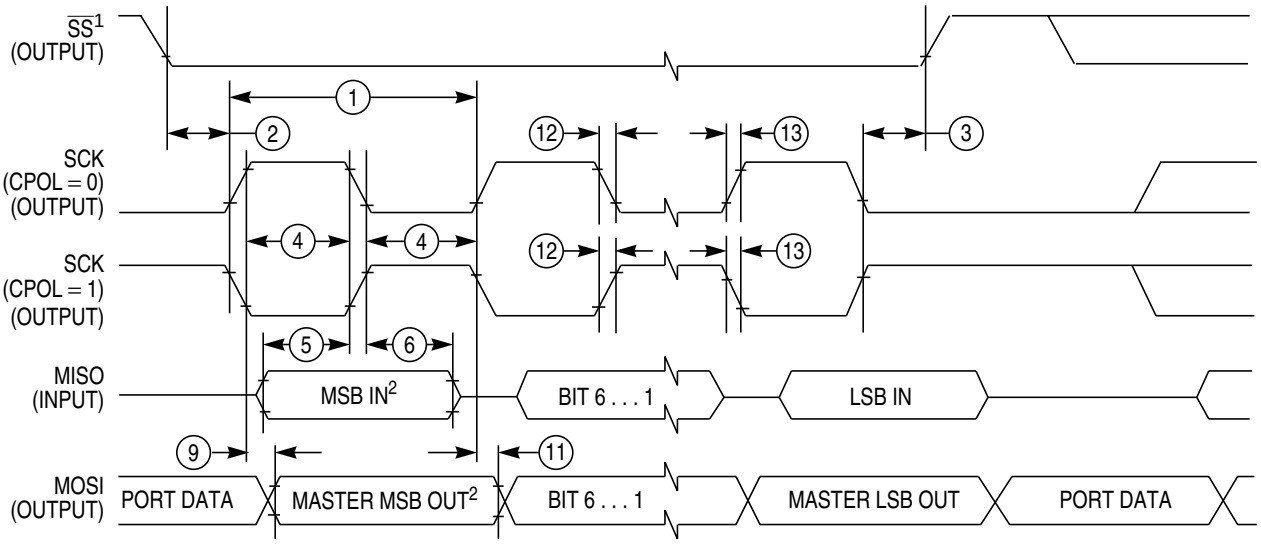
The recovery from Pseudo STOP and Wait are essentially the same since the oscillator was not stopped in both modes. The controller can be woken up by internal or external interrupts. After t_{wrs} the CPU starts fetching the interrupt vector.

A.5.2 Oscillator

The device features an internal Colpitts and Pierce oscillator. The selection of Colpitts oscillator or Pierce oscillator/external clock depends on the $\overline{XCLKS}$ signal which is sampled during reset. Pierce oscillator/external clock mode allows the input of a square wave. Before asserting the oscillator to the internal system clocks the quality of the oscillation is checked for each start from either power-on, STOP or oscillator fail. t_{CQOUT} specifies the maximum time before switching to the internal self clock mode after POR or STOP if a proper oscillation is not detected. The quality check also determines the minimum oscillator start-up time t_{UPOSC} . The device also features a clock monitor. A Clock Monitor Failure is asserted if the frequency of the incoming clock signal is below the Assert Frequency f_{CMFA}.

Table A-15 Oscillator Characteristics

Conditions are shown in **Table A-4** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1a	C	Crystal oscillator range (Colpitts)	f_{OSC}	0.5	-	16	MHz
1b	C	Crystal oscillator range (Pierce) [1]	f_{OSC}	0.5	-	40	MHz
2	P	Startup Current	i_{OSC}	100	-	-	µA
3	C	Oscillator start-up time (Colpitts)	t_{UPOSC}	-	8[2]	100[3]	ms
4	D	Clock Quality check time-out	t_{CQOUT}	0.45	-	2.5	s
5	P	Clock Monitor Failure Assert Frequency	f_{CMFA}	50	100	200	KHz
6	P	External square wave input frequency [4]	f_{EXT}	0.5	-	50	MHz
7	D	External square wave pulse width low [4]	t_{EXTL}	9.5	-	-	ns
8	D	External square wave pulse width high [4]	t_{EXTH}	9.5	-	-	ns
9	D	External square wave rise time [4]	t_{EXTR}	-	-	1	ns
10	D	External square wave fall time [4]	t_{EXTF}	-	-	1	ns
11	D	Input Capacitance (EXTAL, XTAL pins)	C_{IN}	-	7	-	pF
12	C	DC Operating Bias in Colpitts Configuration on EXTAL Pin	V_{DCBIAS}	-	1.1	-	V
13	P	EXTAL Pin Input High Voltage [4]	$V_{IH,EXTAL}$	0.75*V_{DDPLL}	-	-	V
	T	EXTAL Pin Input High Voltage [4]	$V_{IH,EXTAL}$	-	-	V_{DDPLL} + 0.3	V
14	P	EXTAL Pin Input Low Voltage [4]	$V_{IL,EXTAL}$	-	-	0.25*V_{SSPLL}	V
	T	EXTAL Pin Input Low Voltage [4]	$V_{IL,EXTAL}$	V_{SSPLL} - 0.3	-	-	V
15	C	EXTAL Pin Input Hysteresis [4]	$V_{HYS,EXTAL}$	-	250	-	mV



1.If configured as output

2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

Figure A-7 SPI Master Timing (CPHA=1)

In **Table A-19** the timing characteristics for master mode are listed.

Table A-19 SPI Master Mode Timing Characteristics

Num	Characteristic	Symbol	Min	Typ	Max	Unit
1	SCK Frequency	f_{sck}	1/2048	—	1/2	f_{bus}
1	SCK Period	t_{sck}	2	—	2048	t_{bus}
2	Enable Lead Time	t_{lead}	—	1/2	—	t_{sck}
3	Enable Lag Time	t_{lag}	—	1/2	—	t_{sck}
4	Clock (SCK) High or Low Time	t_{wsck}	—	1/2	—	t_{sck}
5	Data Setup Time (Inputs)	t_{su}	8	—	—	ns
6	Data Hold Time (Inputs)	t_{hi}	8	—	—	ns
9	Data Valid after SCK Edge	t_{vsck}	—	—	30	ns
10	Data Valid after $\overline{SS}$ fall (CPHA=0)	t_{vss}	—	—	15	ns
11	Data Hold Time (Outputs)	t_{ho}	20	—	—	ns
12	Rise and Fall Time Inputs	t_{rfi}	—	—	8	ns
13	Rise and Fall Time Outputs	t_{rfo}	—	—	8	ns

A.7.2 Slave Mode

In **Figure A-8** the timing diagram for slave mode with transmission format CPHA=0 is depicted.

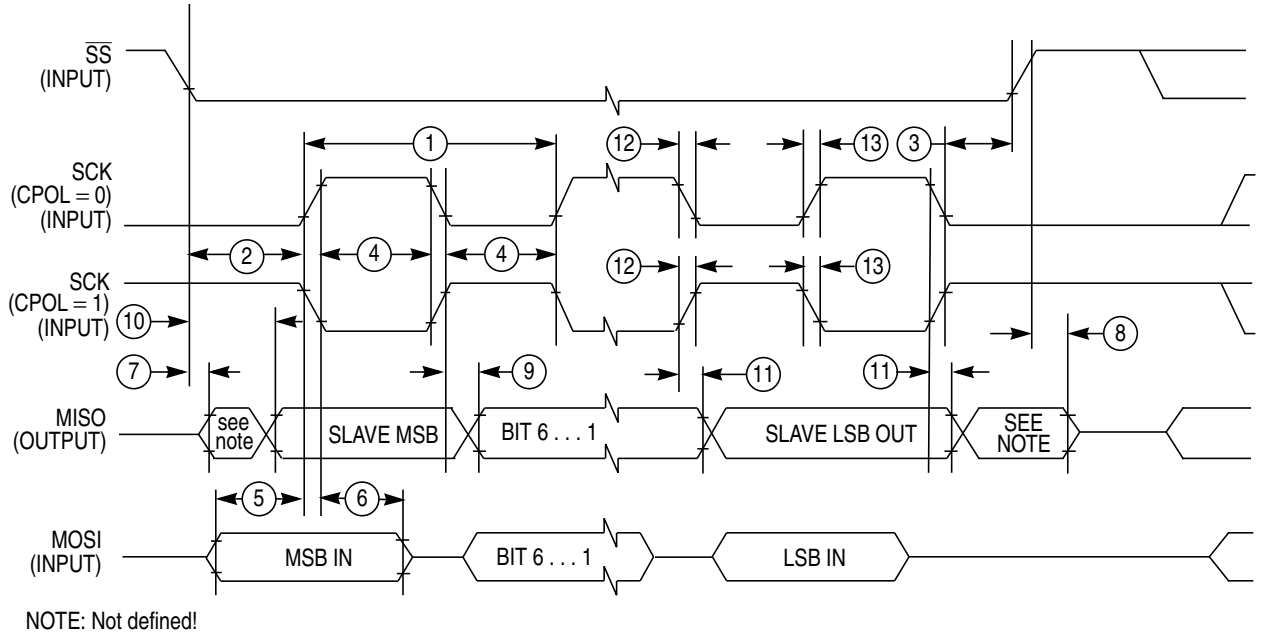


Figure A-8 SPI Slave Timing (CPHA=0)

In **Figure A-9** the timing diagram for slave mode with transmission format CPHA=1 is depicted.

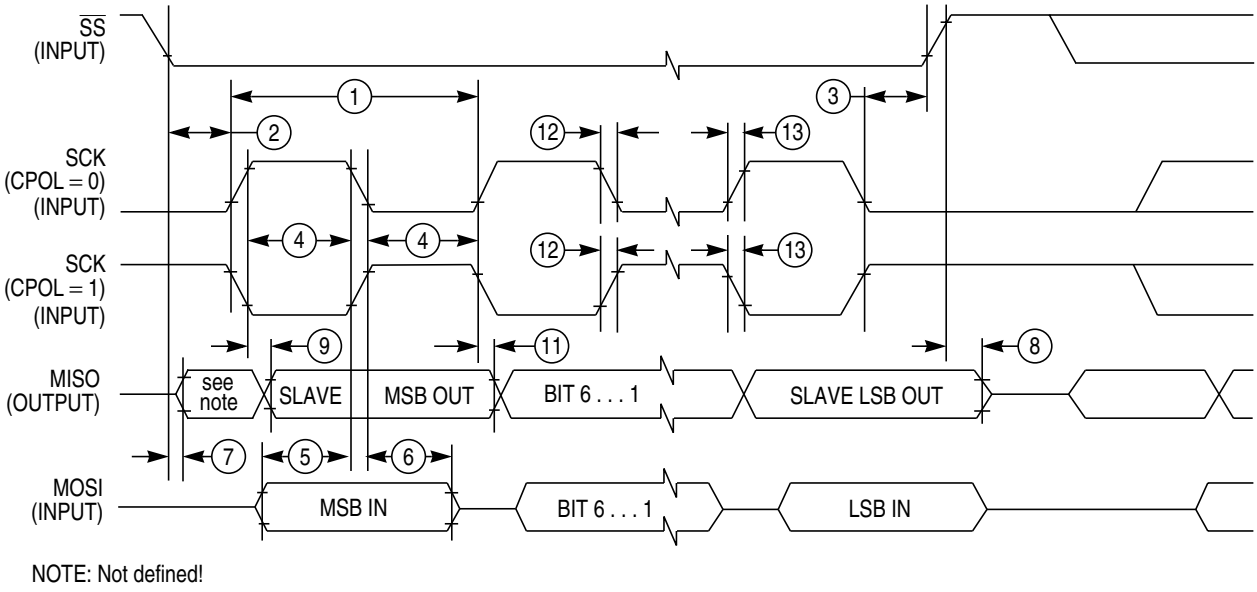


Figure A-9 SPI Slave Timing (CPHA=1)

In **Table A-20** the timing characteristics for slave mode are listed.

Table A-20 SPI Slave Mode Timing Characteristics

Num	Characteristic	Symbol	Min	Typ	Max	Unit
1	SCK Frequency	f_{sck}	DC	—	1/4	f_{bus}
1	SCK Period	t_{sck}	4	—	∞	t_{bus}
2	Enable Lead Time	t_{lead}	4	—	—	t_{bus}
3	Enable Lag Time	t_{lag}	4	—	—	t_{bus}
4	Clock (SCK) High or Low Time	t_{wsck}	4	—	—	t_{bus}
5	Data Setup Time (Inputs)	t_{su}	8	—	—	ns
6	Data Hold Time (Inputs)	t_{hi}	8	—	—	ns
7	Slave Access Time (time to data active)	t_a	—	—	20	ns
8	Slave MISO Disable Time	t_{dis}	—	—	22	ns
9	Data Valid after SCK Edge	t_{vsck}	—	—	30 + t_{bus} [1]	ns
10	Data Valid after $\overline{SS}$ fall	t_{vss}	—	—	30 + t_{bus} [1]	ns
11	Data Hold Time (Outputs)	t_{ho}	20	—	—	ns
12	Rise and Fall Time Inputs	t_{rfi}	—	—	8	ns
13	Rise and Fall Time Outputs	t_{rfo}	—	—	8	ns

NOTES:
1. t_{bus} added due to internal synchronization delay

Appendix B Package Information

B.1 General

This section provides the physical dimensions of the MC9S12DP512 packages.

User Guide End Sheet